

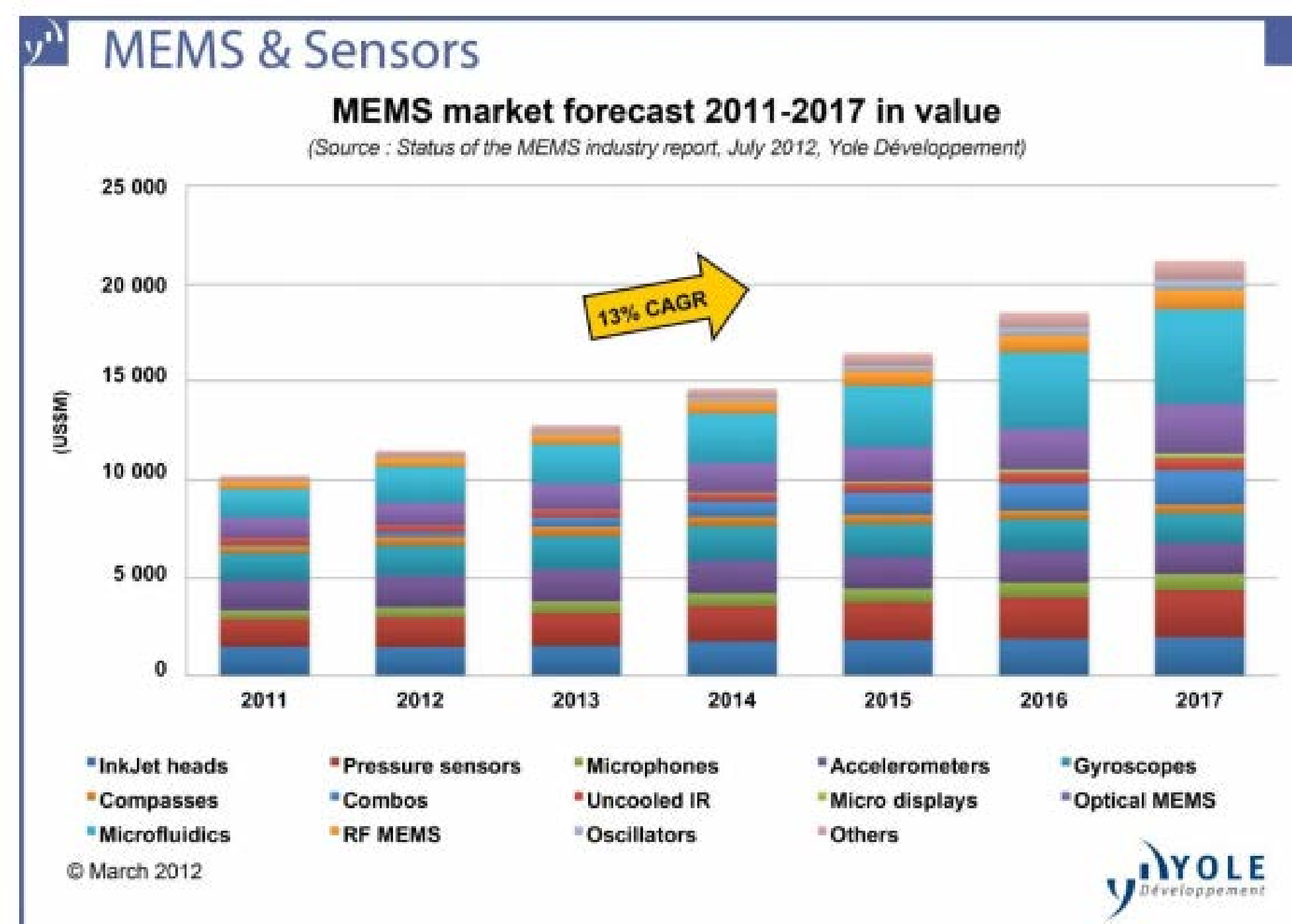
Introduction

- High yield capacitive transduced RF MEMS resonators were built using SOI technology for mass sensing applications
- Air, refilled high K dielectric, and fully solid high K dielectric gaps will be studied
- Highly selective functionalized MEMS biosensing platform using antibody-antigen interaction

Motivation

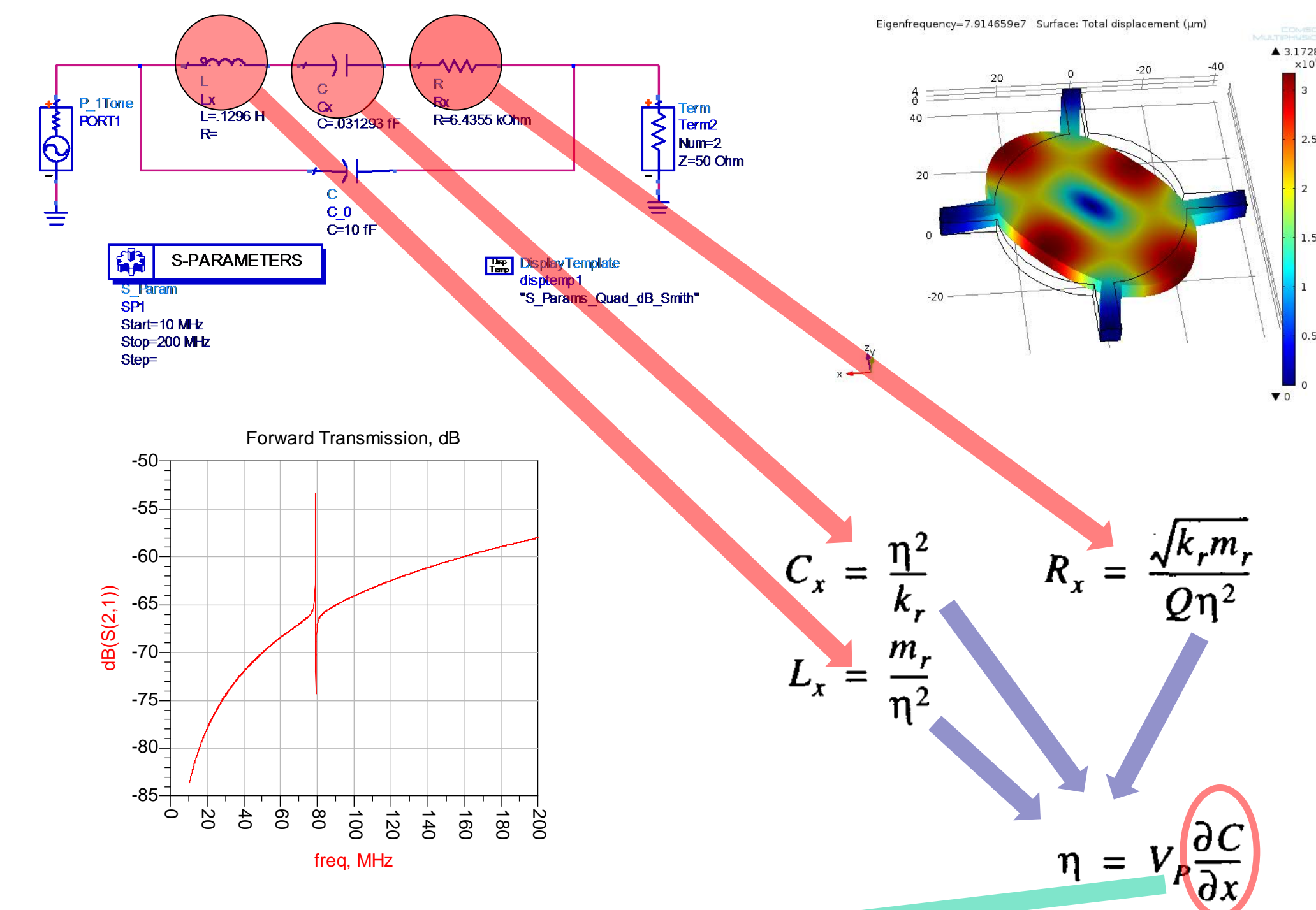
- Electrostatically transduced RF MEMS/NEMS Mechanical resonators have been widely used as mass sensors platforms
- High sensitivity and selectivity with a broad Limit of Detection make these devices ideal for biosensing applications
- MEMS/NEMS technology is one of the fastest growing industries worldwide

Advantages of MEMS/NEMS resonators over other competitive technology					
	M/NEMS Resonator	Nanowires	Solid State Devices	QCM/SAW	Nano SPR
Read out accuracy	High	Medium	Medium	High	High
Limit of detection	ppt	ppt	ppb	ppb	ppb-ppt
Response time	sec	min	min	sec	sec
Manufacturability	YES	Hard	YES	YES	Hard
Miniaturization	YES	YES	YES	Hard	Hard



Simulation

- Using Coventorware, Advanced Design, MathLab, and COMSOL resonator values were approximated



$$C_x = \frac{\eta^2}{k_r}, \quad R_x = \frac{\sqrt{k_r m_r}}{Q\eta^2}, \quad L_x = \frac{m_r}{\eta^2}$$

$$\eta = v_f \frac{\partial C}{\partial x}$$

$$R_x = \frac{K_r}{v_p^2 w_o} * \frac{d_o^4}{A_o^2 \epsilon_o^2 \epsilon_r^2} * \frac{1}{Q(\text{air gap})}$$

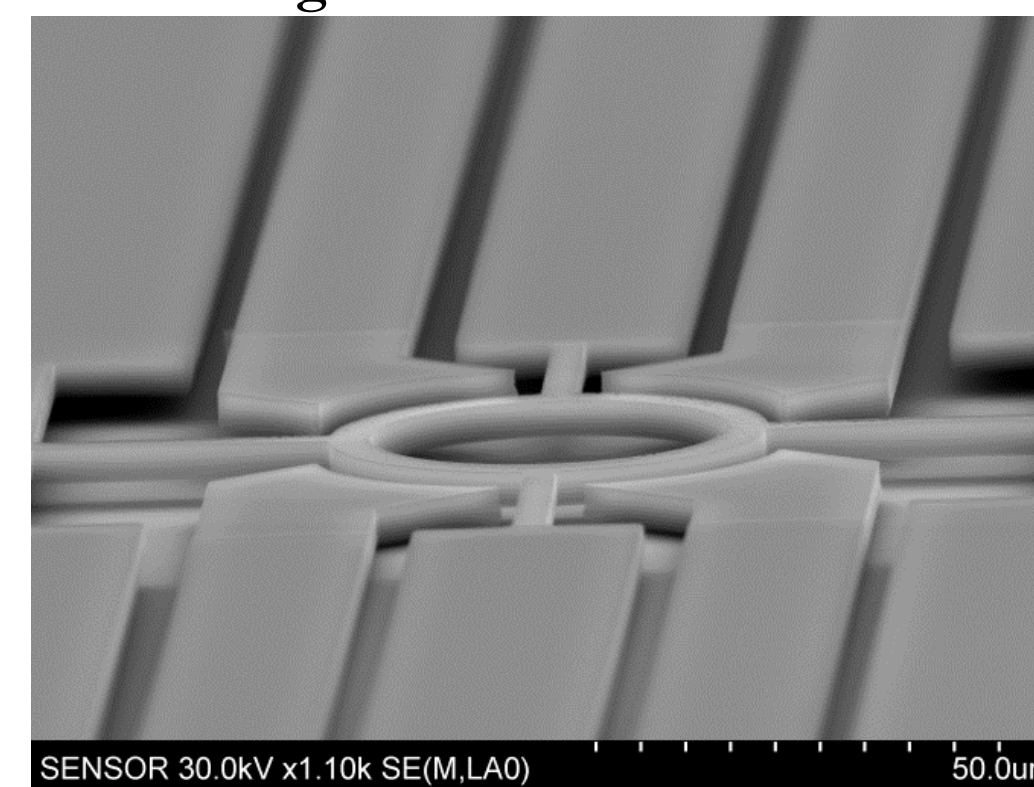
A_o : Electrode Area

ϵ_r : dielectric constant of the device

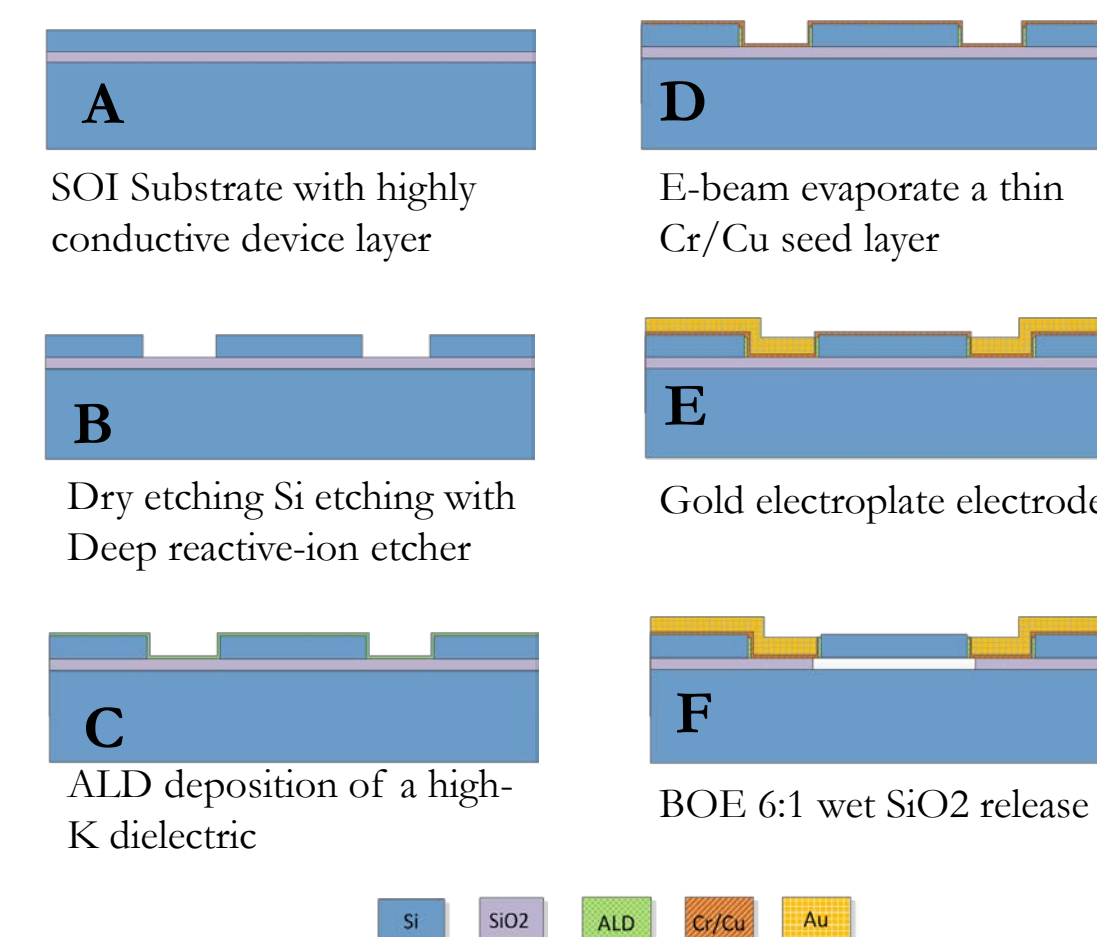
d_o : gap between the disk and electrode

Fabrication

SEM image of fabricated device



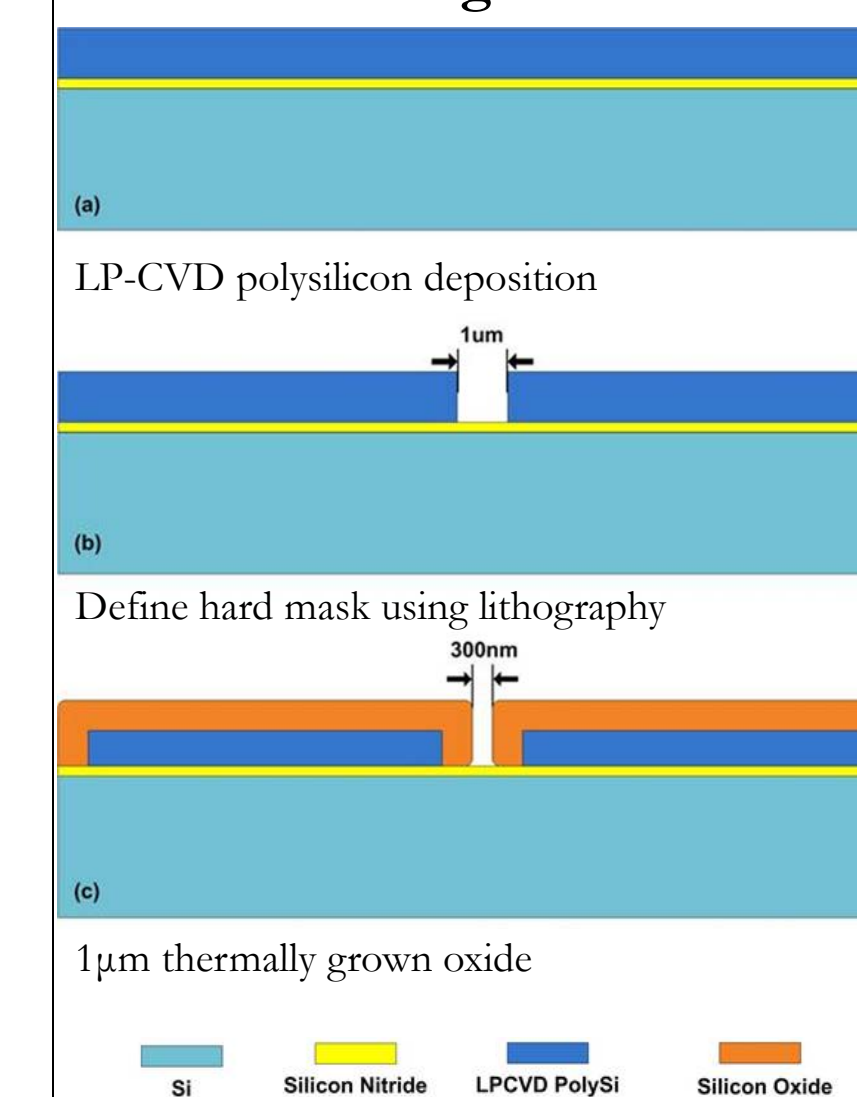
Process flow for a solid gap resonator



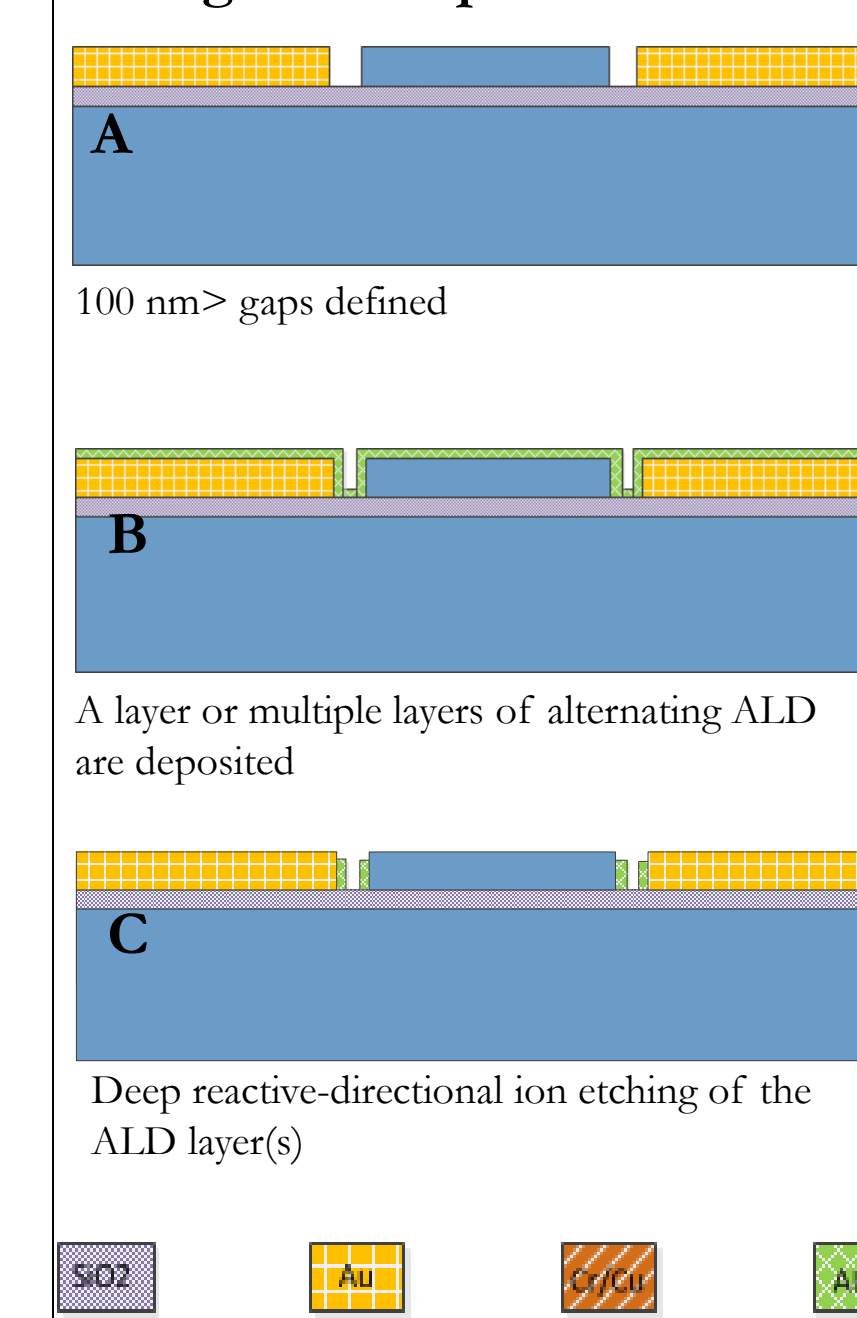
Gap reduction

- Gap reduction is crucial to reduce the characteristic impedance of the device
- Two methods were used: Oxidation and ALD deposition

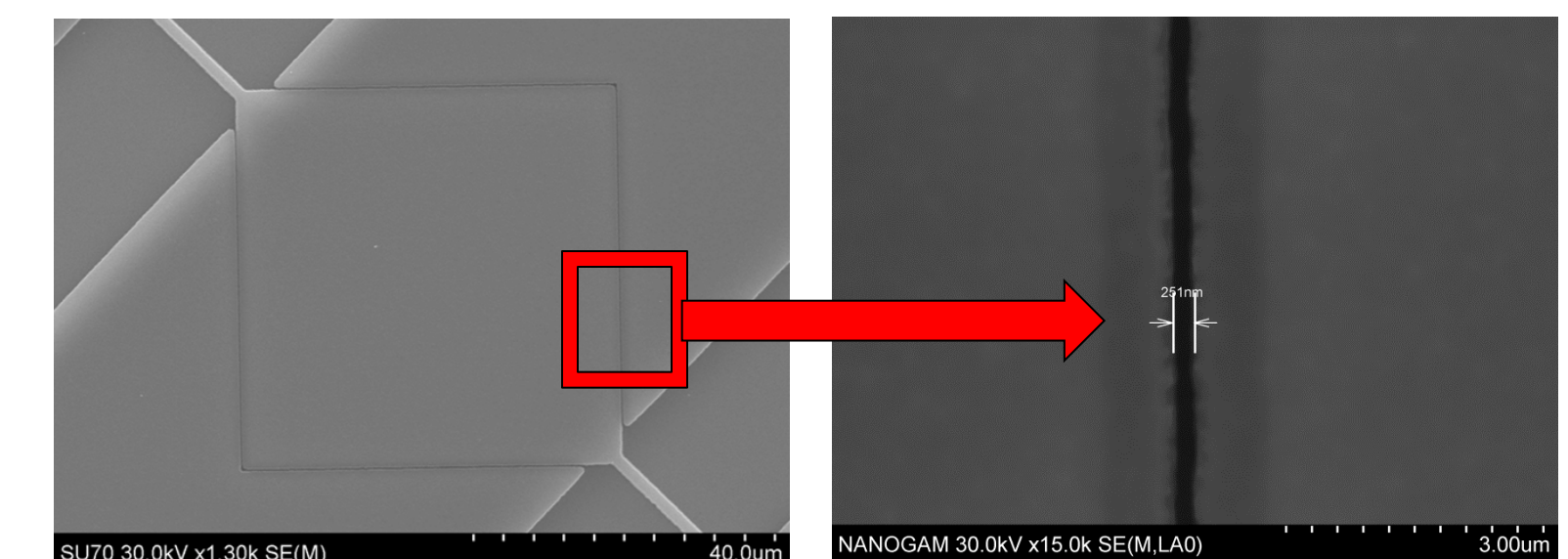
Process flow of gap reduction using Oxidation



Process flow of gap reduction using ALD deposition

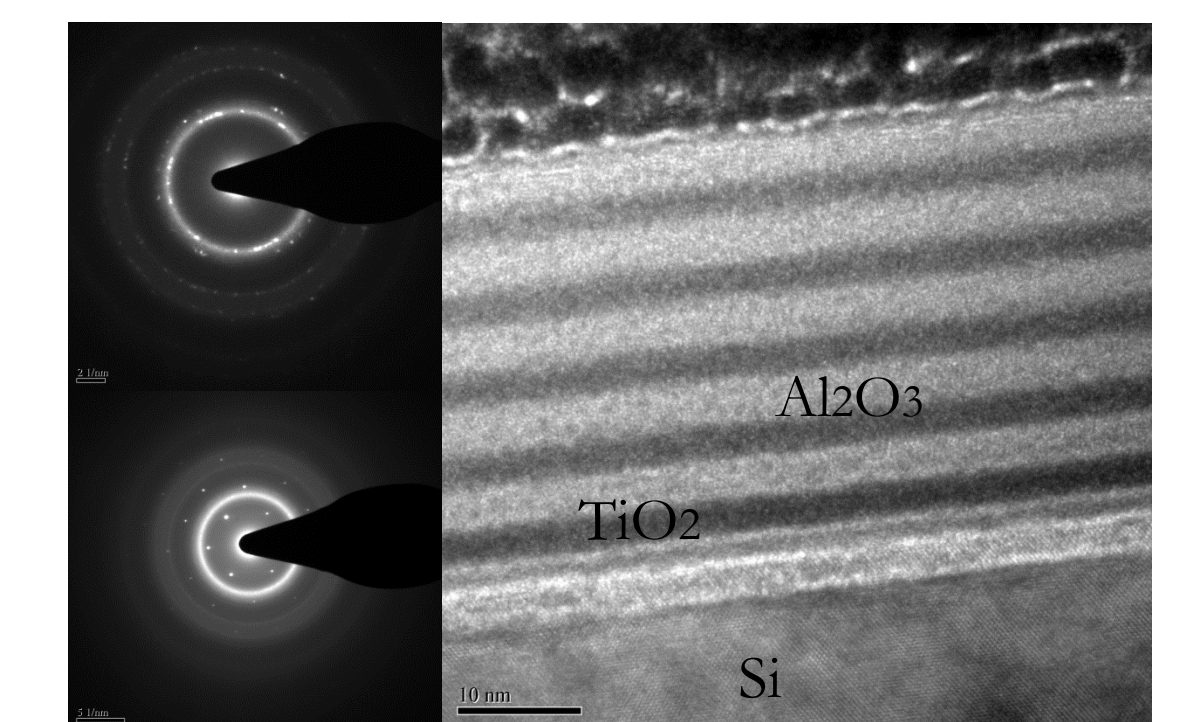


SEM images of oxidation gap reduction



- Reproducible nano-gaps using conventional lithography
- Easy, low-cost and repeatable technique to create nanostructures

TEM image with diffraction pattern of multiple layers of ALD grown and characterized in USF



- Atomically controlled thickness
- Low temperature process (~100 C°)
- Very conformal process
- High K dielectric materials

Future Work

- Highly selective capacitive-transduced biosensor
- CMOS compatible biosensor
- Microfluidic Lab-in-a-chip biosensor